

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	55	(device or ic or integrated adj circuit or die or chip or semiconductor or wafer) near3 (carrier or tray or chuck or support or housing or package or packaging or interposer or holder or socket) same (magnet or magnetic) near (top or cover or lid)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/30 08:45
L2	150	(carrier or tray or chuck or support or housing or package or packaging or interposer or holder) with (temporar\$3) with (die or device or chip or wafer or ic or integrated adj circuit or element or module or component) and (cover or lid) near3 (recess or recessed or planar)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/30 09:10
L10	21	257/710.cds. and (magnet or magnetic or magnetically or magnetism or ferromagnet or ferromagnetically or ferromagnetism or ferromagnetic)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/30 09:27
L12	22	257/729.cds. and (magnet or magnetic or magnetically or magnetism or ferromagnet or ferromagnetically or ferromagnetism or ferromagnetic)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/30 09:51
L14	380	(package or housing or packaging or carrier or transport or tray or holder or chuck) near4 (chip or die or ic or circuit or device or wafer) same (lid or cover or seal or sealing) near3 (magnet or magnetic or magnetically or magnetism or ferromagnet or ferromagnetically or ferromagnetism or ferromagnetic)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/30 09:53
S6	149	(wafer or die or chip or substrate or ic or integrated adj circuit) near3 (carrier or holder or support or package or chuck) and (carrier or holder or support or package or chuck) near6 (indent or indentation or indented or groove or grooved or depression or depressed or recess or recessed) near5 (magnet or ferrous or magnetic or magnetically)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/29 14:31
S19	71	(low near profile) near5 (carrier or holder or support or package or chuck or support or plate or base) and ((magnet or magnetic or magnetically or ferrous or electrostatic or electrostatically) near (fasten\$3 or bound or binding or affix\$3 or hold\$3 or held or seal\$3 or adher\$3 or lock\$3 or bind or mount\$3 or secured or securing or clamp\$3))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/29 14:43
S21	88	(wafer or die or chip or substrate or integrated adj circuit or ic) near3 (carrier or holder or support or package or mounting) near3 (test or probe or testing or temporary) and (lid or cover or holder or seal or ring or binding or binder) near10 (magnet or magnetic or ferromagnet or ferrous or ferride or electromagnet\$2)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/29 14:52
S30	124	(electronics or device) near3 (carrier or holder or support or package or mounting or chuck) near3 (test or probe or testing or temporary) and (lid or cover or holder or seal or ring or binding or binder) near10 (magnet or magnetic or ferromagnet or ferrous or ferride or electromagnet\$2)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/29 15:59
S31	156	(electronics or device) near (carrier or holder or support or package or mounting or chuck or module or packaging or housing) and (carrier or holder or support or package or packaging or mounting or chuck or module or housing) near5 (lid or cover) near2 (magnet or magnetic or magnetically or ferromagnetically or ferromagnet or ferrous or ferride or electromagnet\$6)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/29 16:14
S35	164	(low or small) near (profile or height) near (carrier or holder or support or package or mounting or chuck or module or packaging or housing) and (semiconductor or die or wafer or substrate or chip or ic or integrated near circuit or device or module) near3 (groove or recess or depression or trench or indent or indentation)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/29 16:27

S40	196	(die or chip or ic or module or integrated near circuit or device or semiconductor or wafer) near2 (carrier or holder or support or package or mounting or chuck or module or packaging or housing or socket) and (wafer or substrate) near (probe or prober or probing or probed) near (test or testing or tester or tested) and (cover or lid)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/29 16:41
S41	113	(wafer or round or circular or disc) near2 (form or formed or shaped or shape) near2 (carrier or holder or support or package or mounting or chuck or module or packaging or housing or socket) same (wafer or substrate or die or ic or chip or component) near2 (cleaved or sawed or singulated or singulation or cleaving or cut or diced or dicing)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/29 16:58
S45	180	(low adj profile) near2 (carrier or tray or chuck or support or housing or package or packaging or interposer or holder) same (lid or cover)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/29 17:10
S50	53	(device or ic or integrated adj circuit or die or chip or semiconductor or wafer) near3 (carrier or tray or chuck or support or housing or package or packaging or interposer or holder or socket) same (magnet or magnetic) near (top or cover or lid)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/30 08:44
S65	145	(carrier or tray or chuck or support or housing or package or packaging or interposer or holder) with (temporar\$3) with (die or device or chip or wafer or ic or integrated adj circuit or element or module or component) and (cover or lid) near3 (recess or recessed or planar)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/30 08:58
S89	161	(wafer or die or chip or substrate or ic or integrated adj circuit) near3 (carrier or holder or support or package or chuck) and (carrier or holder or support or package or chuck) near6 (indent or indentation or indented or groove or grooved or depression or depressed or recess or recessed) near5 (magnet or ferrous or magnetic or magnetically)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/29 14:31
S90	79	(low near profile) near5 (carrier or holder or support or package or chuck or support or plate or base) and ((magnet or magnetic or magnetically or ferrous or electrostatic or electrostatically) near (fasten\$3 or bound or binding or affix\$3 or hold\$3 or held or seal\$3 or adher\$3 or lock\$3 or bind or mount\$3 or secured or securing or clamp\$3))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/29 14:44
S91	97	(wafer or die or chip or substrate or integrated adj circuit or ic) near3 (carrier or holder or support or package or mounting) near3 (test or probe or testing or temporary) and (lid or cover or holder or seal or ring or binding or binder) near10 (magnet or magnetic or ferromagnet or ferrous or ferride or electromagnet\$2)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/29 14:54
S92	129	(electronics or device) near3 (carrier or holder or support or package or mounting or chuck) near3 (test or probe or testing or temporary) and (lid or cover or holder or seal or ring or binding or binder) near10 (magnet or magnetic or ferromagnet or ferrous or ferride or electromagnet\$2)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/29 16:02
S93	164	(electronics or device) near (carrier or holder or support or package or mounting or chuck or module or packaging or housing) and (carrier or holder or support or package or packaging or mounting or chuck or module or housing) near5 (lid or cover) near2 (magnet or magnetic or magnetically or ferromagnetically or ferromagnet or ferrous or ferride or electromagnet\$6)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/29 16:14
S94	179	(low or small) near (profile or height) near (carrier or holder or support or package or mounting or chuck or module or packaging or housing) and (semiconductor or die or wafer or substrate or chip or ic or integrated near circuit or device or module) near3 (groove or recess or depression or trench or indent or indentation)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/29 16:28

S95	211	(die or chip or ic or module or integrated near circuit or device or semiconductor or wafer) near2 (carrier or holder or support or package or mounting or chuck or module or packaging or housing or socket) and (wafer or substrate) near (probe or prober or probing or probed) near (test or testing or tester or tested) and (cover or lid)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/29 16:42
S96	128	(wafer or round or circular or disc) near2 (form or formed or shaped or shape) near2 (carrier or holder or support or package or mounting or chuck or module or packaging or housing or socket) same (wafer or substrate or die or ic or chip or component) near2 (cleaved or sawed or singulated or singulation or cleaving or cut or diced or dicing)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/29 16:59
S97	191	(low adj profile) near2 (carrier or tray or chuck or support or housing or package or packaging or interposer or holder) same (lid or cover)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/29 17:10